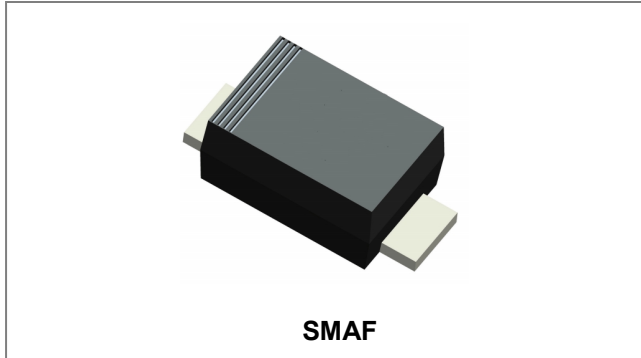


**SS32AF THRU SS320AF SCHOTTKY RECTIFIER**



**Features**

- Schottky Barrier Rectifier
- Guard Ring Die Protection
- Low Forward Voltage
- Reverse Energy Tested
- High Current Capability
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- This is a Halogen Free device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

**Circuit Diagram**



**Mechanical Data**

- Case: JEDEC SMAF molded plastic body
- Terminals: leads solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.038 grams
- Mounting Position: Any

**Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified**

Characteristic	Symbol	SS32 AF	SS33 AF	SS35 AF	SS36 AF	SS38 AF	SS310 AF	SS315 AF	SS320 AF	Units
Maximum Repetitive Peak Reverse Voltage Maximum DC Blocking Voltage	V <sub>RRM</sub> V <sub>DC</sub>	20	30	50	60	80	100	150	200	V
Maximum RMS Voltage	V <sub>RMS</sub>	14	21	35	42	56	70	105	150	V
Maximum Average Forward Rectified Current at T <sub>L</sub> (see fig.1)	I <sub>F(AV)</sub>	3.0								A
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	70								A
Maximum Instantaneous Forward Voltage @ I <sub>F</sub> = 3.0A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.55	0.70	0.85				0.95	V	
Maximum DC Reverse Current @T <sub>J</sub> = 25°C At Rated DC Blocking Voltage @T <sub>J</sub> = 100°C	I <sub>R</sub>	0.5				0.1				mA
		20				10	2.0			
Typical Junction Capacitance(Note 1)	C <sub>J</sub>	500			300				pF	
Typical Thermal Resistance Junction to Ambient(Note 2)	R <sub>θJA</sub>	80								°C/W
Operating Temperature Range	T <sub>J</sub>	-55 to +125				-55 to +150				°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150								°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
2. P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

**Ratings and Characteristics Curves**

FIG.1-FORWARD CURRENT DERATING CURVE

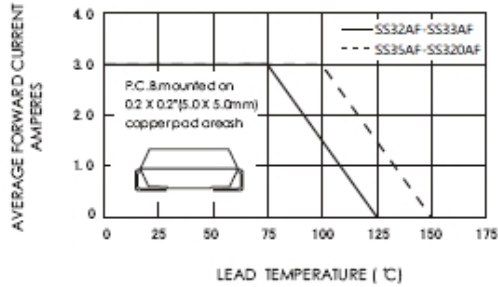


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

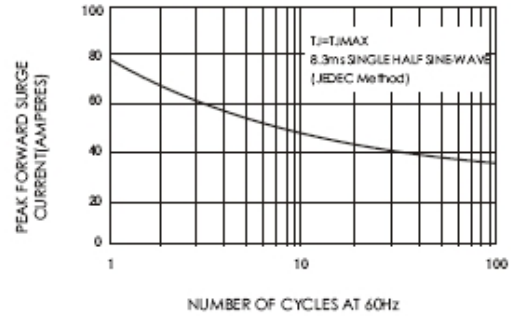


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

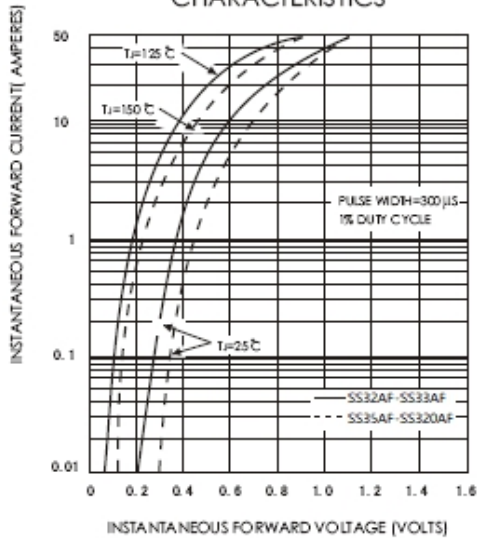


FIG.4-TYPICAL REVERSE CHARACTERISTICS

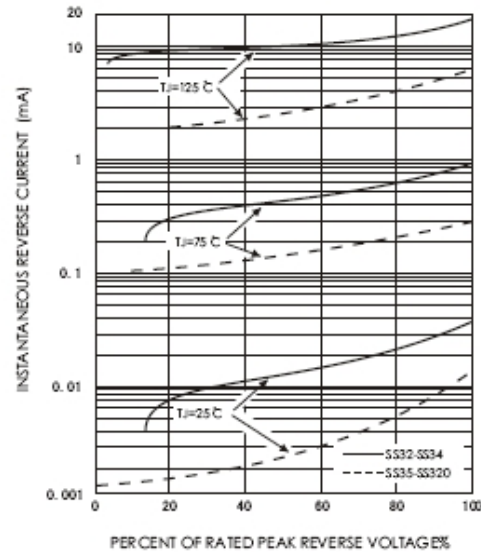


FIG.5-TYPICAL JUNCTION CAPACITANCE

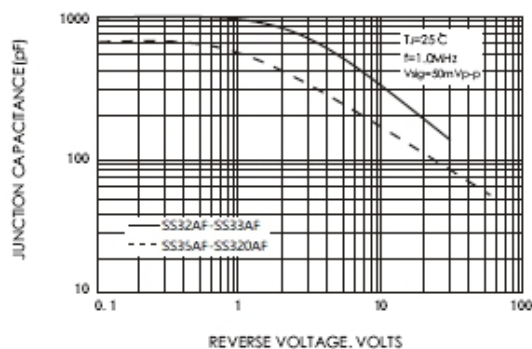
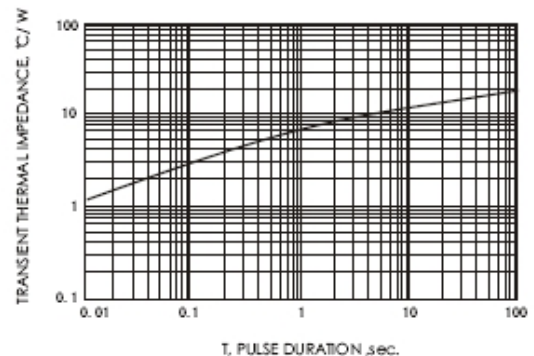
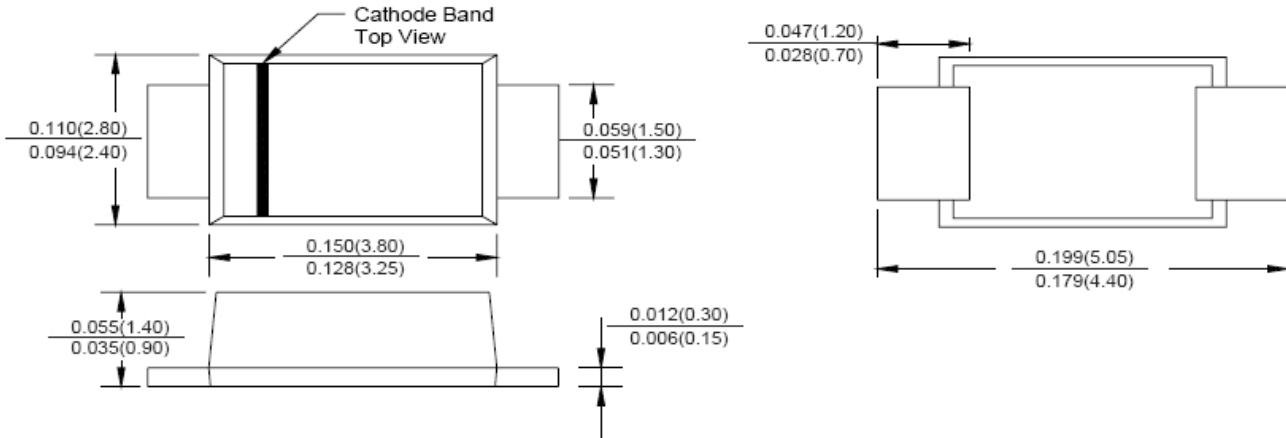


FIG.6-TYPICAL TRANSIENT THERMAL IMPEDANCE



**Mechanical Dimensions SMAF (Millimeters/Inches)**

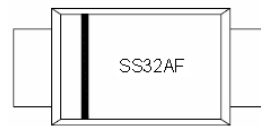


**Ordering Information**

Device	Package	Shipping
SS32AF THRU SS320AF	SMAF	3000pcs / reel
SS32AFTR THRU SS320AFTR	SMAF	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

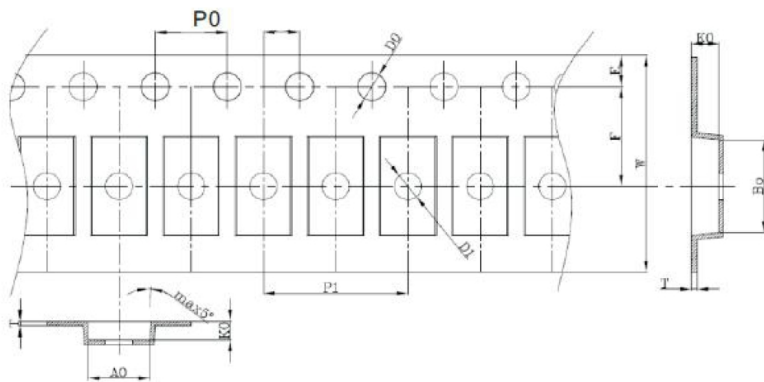
**Marking Diagram**



Where XXXXX is YYWWL  
YYWWL date code marked on box.

SS32AF = Part Name  
YY = Year  
WW = Week  
L = Lot Number

**Carrier Tape Specification SMAF**



SYMBOL	Millimeters	
	Min.	Max.
A0	2.83	3.03
B0	2.23	5.43
K0	1.23	1.43
P0	3.90	4.10
P1	3.90	4.10
P2	1.90	2.10
T	0.17	0.23
E	1.63	1.83
F	5.45	5.65
D0	1.50	1.60
D1	1.45	1.55
W	11.70	12.30



**SS32AF  
THRU  
SS320AF**

**Technical Data  
Data Sheet N1949, Rev. A**



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